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Docket No.: 0033-1048PUS1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shinji TAKASE et al.

International Application No.: PCT/JP2004/019164

Application No.: NEW

Art Unit: N/A

Filed: December 27, 2005

Examiner: Not Yet Assigned

For: METHOD OF RESIN SEALING OF
ELECTRONIC COMPONENT AND MOLD
USED IN THE METHOD

PRELIMINARY AMENDMENT

MS Assignment Recordation Services
Director of the US Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

The following preliminary amendments and remarks are respectfully submitted in connection with the above-identified application.

This amendment includes:

Amendments to the Abstract begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 4 of this paper.

Abstract of the Disclosure begin on page 5 of this paper.